Silicon N-Channel MOS FET UHF Power Amplifier

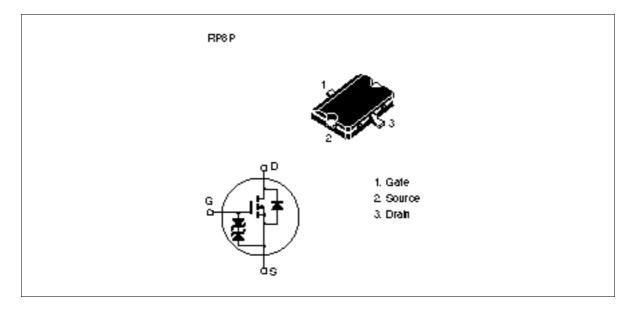


1st. Edition

Features

- High power output, High gain, High efficiency $PG = 7.8 dB, Pout = 37.3 dBm, \eta D = 50 \ \% min. \ (f = 836.5 MHz)$
- Compact package capable of surface mounting

Outline



This Device is sensitive to Elector Static Discharge. An Adequate handling procedure is requested.



Absolute Maximum Ratings (Ta = 25° C)

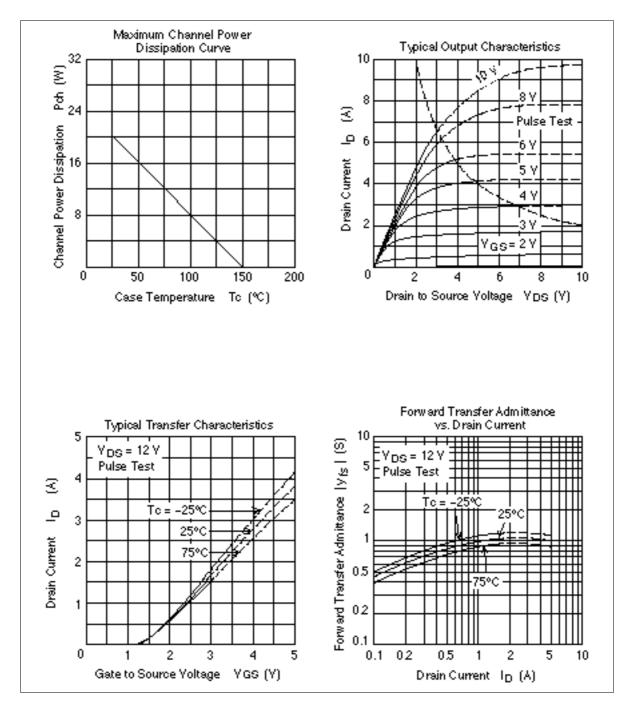
Item	Symbol	Ratings	Unit	
Drain to source voltage	V _{DSS}	17	V	
Gate to source voltage	V _{GSS}	±10	V	
Drain current	ID	1.1	A	
Drain peak current	I _{D(pulse)} * ¹	5	A	
Channel dissipation	Pch* ²	20	W	
Channel temperature	Tch	150	°C	
Storage temperature	Tstg	-45 to +150	°C	

Notes: 1. $PW \le 10\mu s$, duty cycle $\le 1 \%$

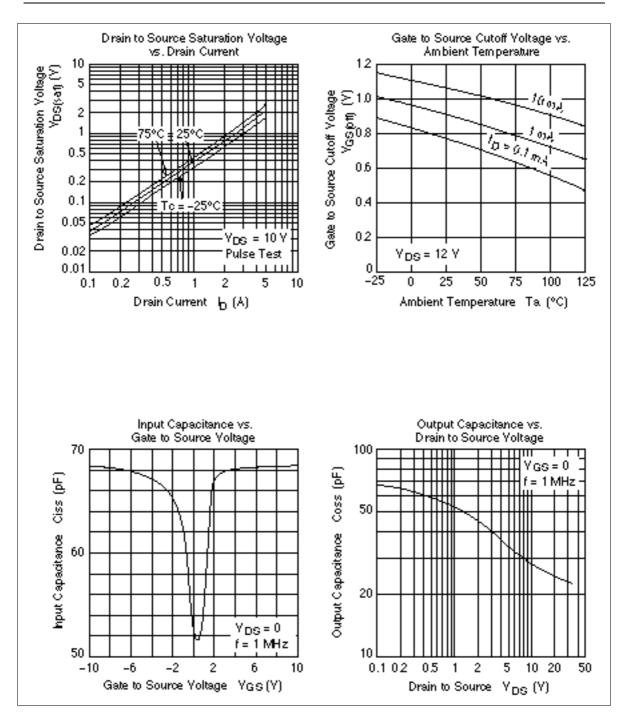
2. Value at Tc = 25°C

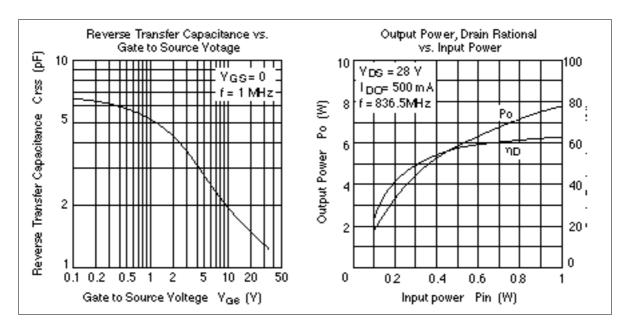
Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min.	Тур	Max.	Unit	Test Conditions
Zero gate voltage drain current	I _{DSS}	_	—	10	μA	$V_{DS} = 12 V, V_{GS} = 0$
Gate to source leak current	I _{GSS}	_	_	±5.0	μA	$V_{GS} = \pm 10V, V_{DS} = 0$
Gate to source cutoff voltage	$V_{\text{GS(off)}}$	0.6	_	1.3	V	$I_D = 6mA, V_{DS} = 12V$
Input capacitance	Ciss	—	68		pF	$V_{GS} = 5V, V_{DS} = 0$ f = 1MHz
Output capacitance	Coss	—	27	_	pF	$V_{DS} = 12V, V_{GS} = 0$ f = 1MHz
Output Power	Pout	37.3	38.45	—	dBm	V _{DS} = 12V, f = 836.5MHz Pin = 29.5dBm
Drain Rational	ηD	50	60	_	%	V _{DS} = 12V Pout = 37.3dBm f = 836.5MHz Pin = 29.5dBm

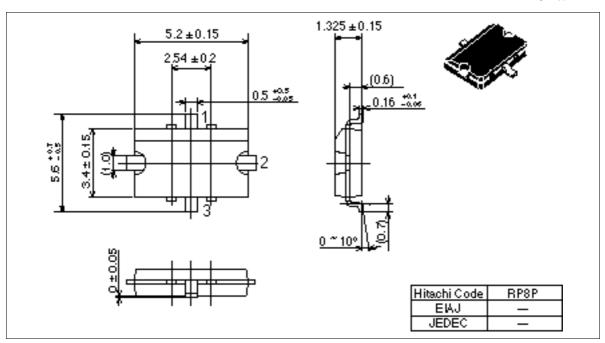


Main Characteristics





Package Dimensions



Unit: mm

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